



HJ2955

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HJ2955 is designed for general purpose of amplifier and switching applications.

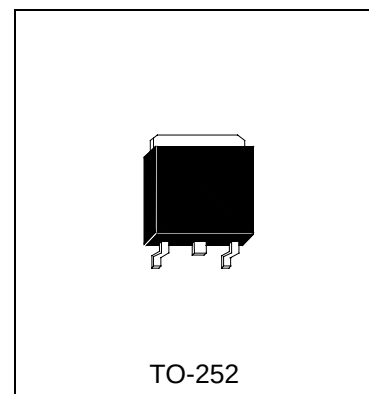
Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature 150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
BVCEO Collector to Base Voltage -70 V
BVCEO Collector to Emitter Voltage -60 V
BVEBO Emitter to Base Voltage -5 V
IC Collector Current -10 A
IB Base Current -6 A

Characteristics (Ta=25°C)

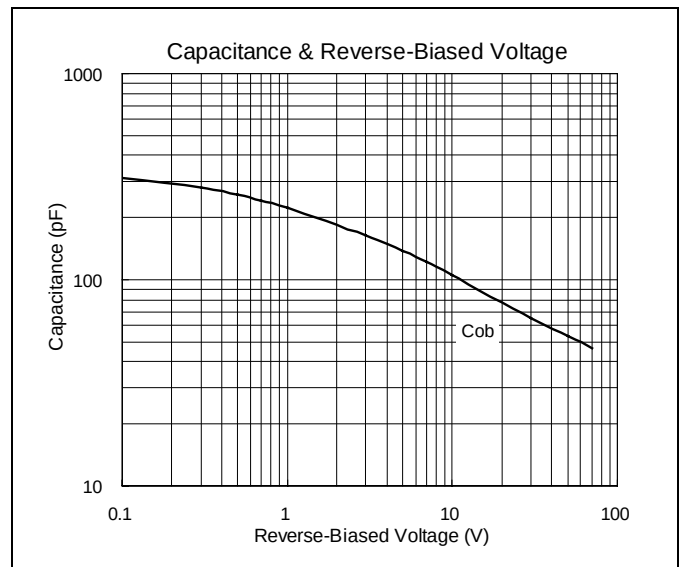
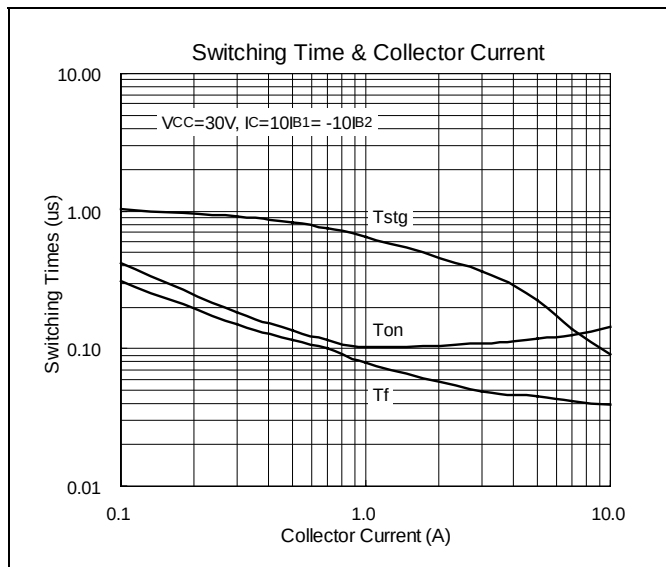
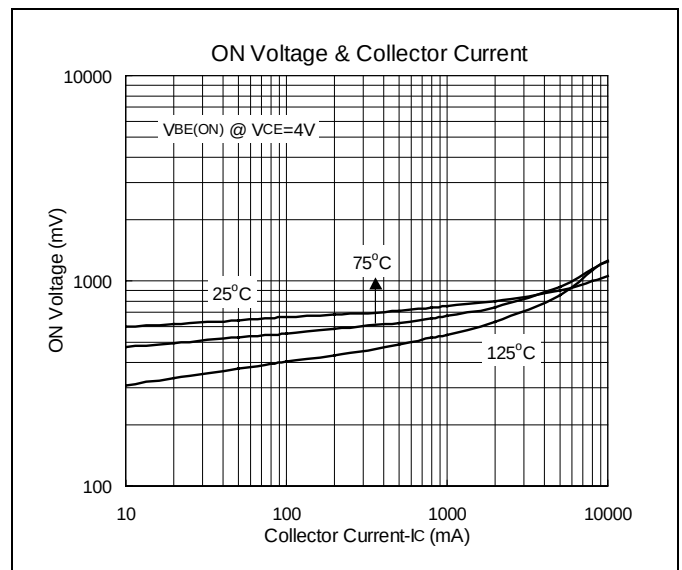
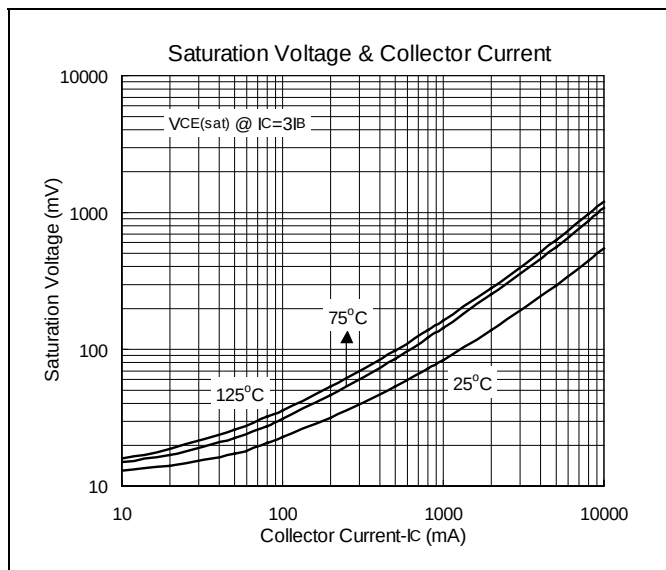
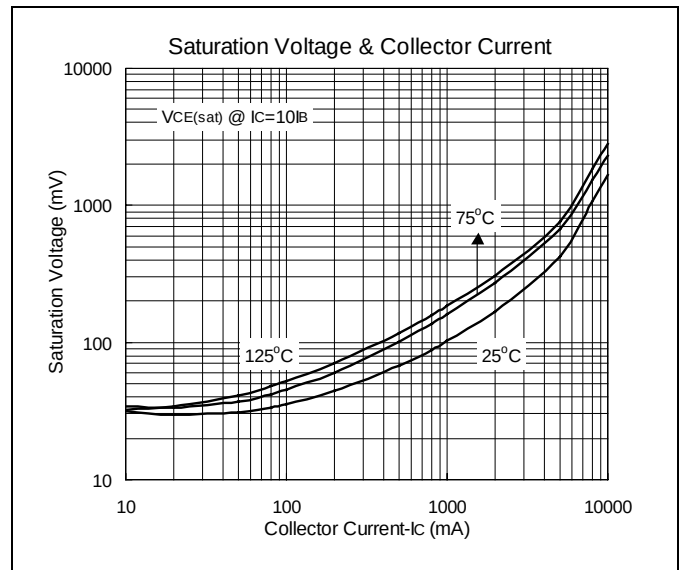
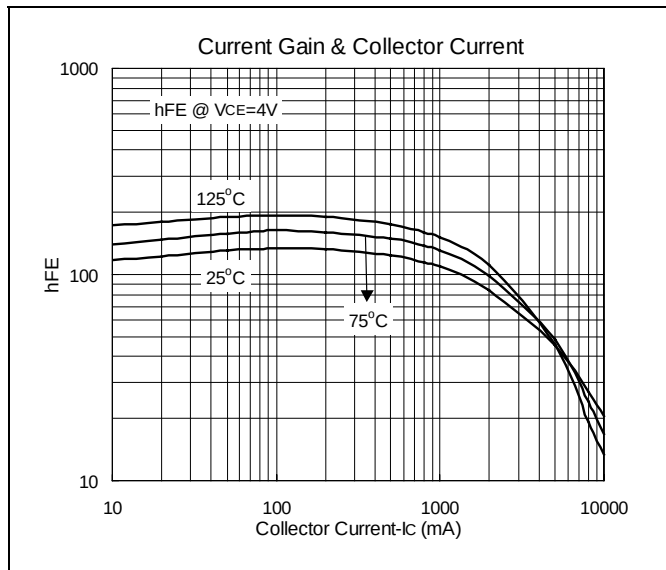
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	-60	-	-	V	IC=-30mA, IB=0
BVCBO	-70	-	-	V	IC=-1mA, IE=0
BVEBO	-5	-	-	V	IE=-1mA, IC=0
ICBO	-	-	-20	uA	VCB=-70V, IE=0
ICEX	-	-	-20	uA	VCE=-70V, VEB(off)=-1.5V
ICEO	-	-	-50	uA	VCE=-30V, IB=0
IEBO	-	-	-0.5	mA	VEB=-5V, IC=0
*VCE(sat)1	-	-	-1.1	V	IC=-4A, IB=-400mA
*VCE(sat)2	-	-	-8	V	IC=-10A, IB=-3.3A
*VBE(on)	-	-	-1.8	V	IC=-4A, VCE=-4V
*hFE1	20	-	100		IC=-4A, VCE=-4V
*hFE2	5	-	-		IC=-10A, VCE=-4V
fT	2	-	-	MHz	VCE=-10V, IC=-500mA, f=1MHz

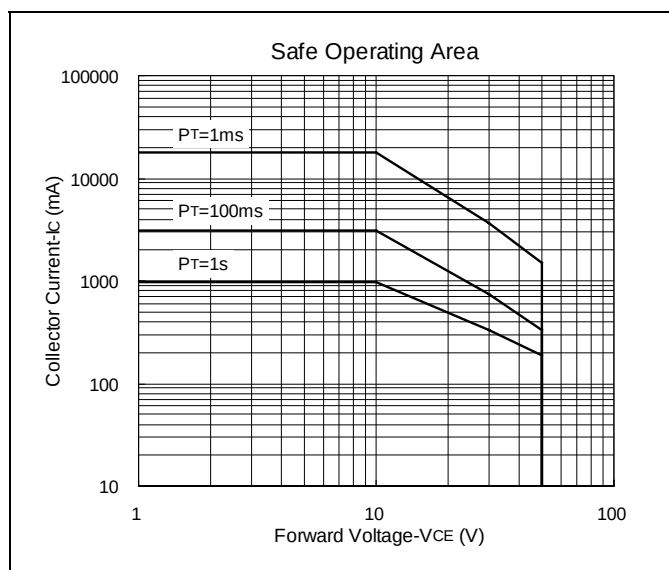
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%





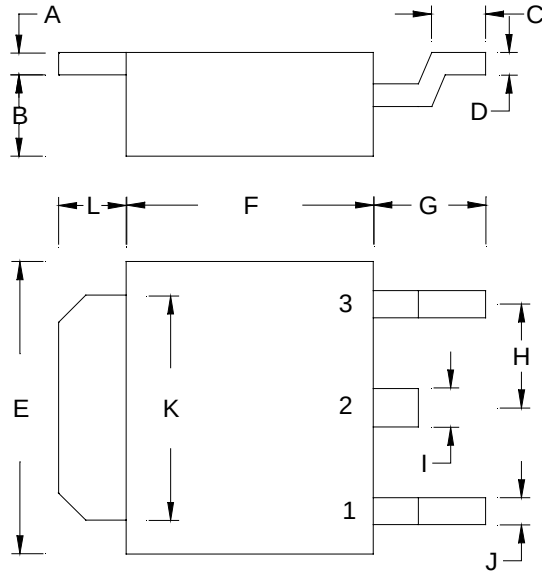
Characteristics Curve





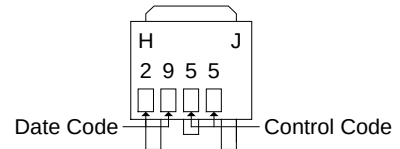


TO-252 Dimension



3-Lead TO-252 Plastic Surface Mount Package
HSMC Package Code: J

Marking:



Style: Pin 1.Base 2.Collector 3.Emitter

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes: 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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